



FOR SEMI

FS2312 大封装

## N-Channel Enhancement Mode MOSFET

### ● Features

$V_{DS}=20V$

$R_{DS(ON)} = 21m\Omega @ V_{GS} = 4.5V, I_D = 5.0A$

$R_{DS(ON)} = 24m\Omega @ V_{GS} = 2.5V, I_D = 4.5A$

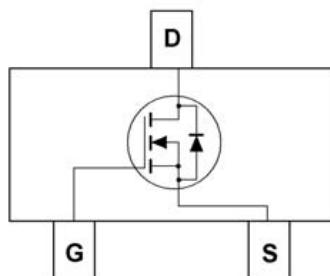
$R_{DS(ON)} = 50m\Omega @ V_{GS} = 1.8V, I_D = 4.0A$

Advanced trench process technology

High Density Cell Design For Ultra Low On-Resistance

SOT23-3L for Surface Mount Package

### ● Pin Configurations



SOT23-3L

### ● Absolute Maximum Ratings @ $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Drain Current-Continuous	$I_D$	4.9	A
Pulsed Drain Current	$I_{DM}$	15	
Maximum Power Dissipation	$T_A = 25^\circ C$	0.75	W
		0.48	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	°C
Junction-to-Ambient Thermal Resistance (PCB mounted)	$R_{JA}$	140	°C/W



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- Electrical Characteristics @ $T_A=25^\circ C$  unless otherwise noted

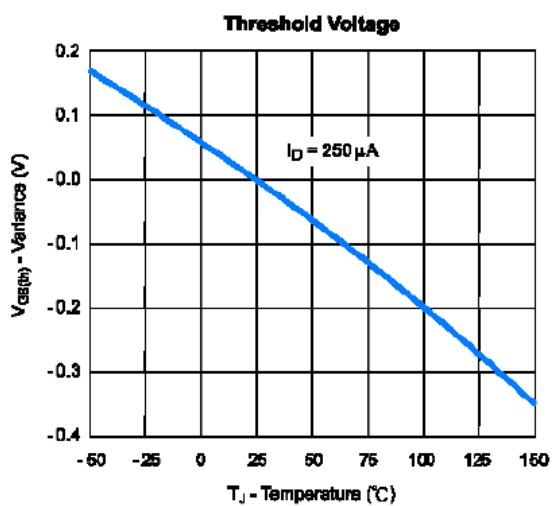
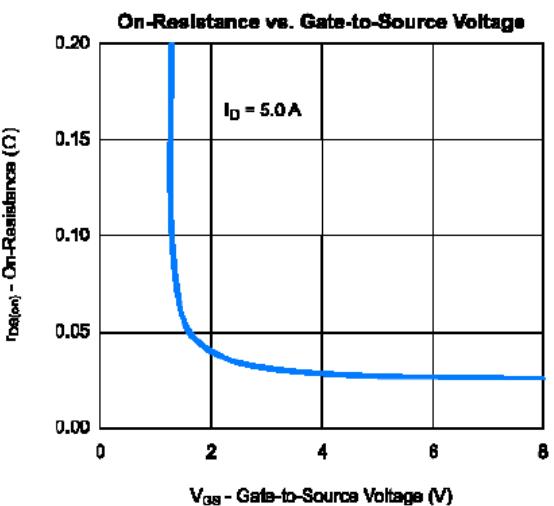
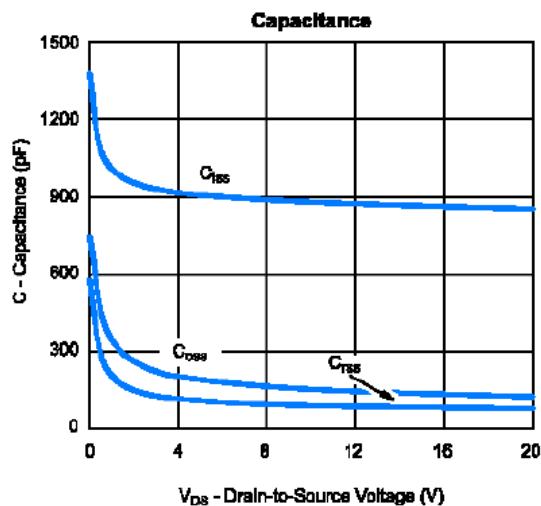
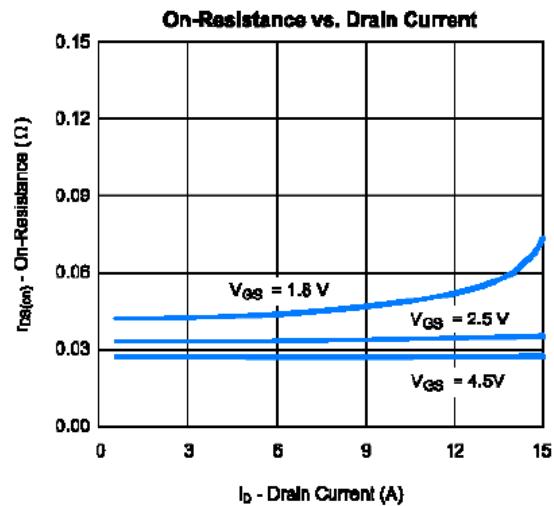
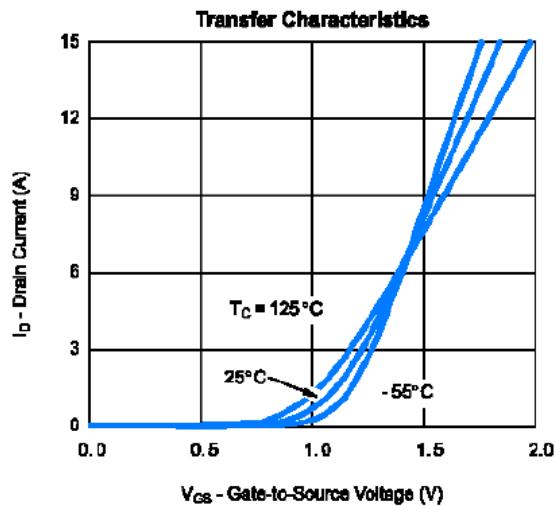
Parameter	Symbol	Test Conditions	Min	Typ.	Max	Units
<b>Static</b>						
Drain to Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	20	--	--	V
Zero-Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=20V, V_{GS}=0V$	--	--	1	$\mu A$
Gate Body Leakage Current, Forward	$I_{GSSF}$	$V_{GS}=8V, V_{DS}=0V$	--	--	100	nA
Gate Body Leakage Current, Reverse	$I_{GSSR}$	$V_{GS}=-8V, V_{DS}=0V$	--	--	-100	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	0.4	--	1	V
Static Drain-source On-Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=5.0A$	--	21	31	$m\Omega$
		$V_{GS}=2.5V, I_D=4.5A$	--	24	37	$m\Omega$
		$V_{GS}=1.8V, I_D=4.0A$		50	85	$m\Omega$
Forward Transconductance	$g_f$	$V_{DS}=15V, I_D=5.0A$		40		S
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Max. Diode Forward Current	$I_S$				1.7	A
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=1.8A$	--	--	1.2	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=10V, I_D=5.0A,$ $V_{GS}=4.5V$		11.2	14	nC
Gate-Source Charge	$Q_{gs}$			1.4		
Gate-Drain Charge	$Q_{gd}$			2.2		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=10V, R_L=10\Omega, I_D=1A,$ $V_{GEN}=4.5V \quad R_G=6\Omega$		15	25	ns
Turn-On Rise Time	$t_r$			40	60	
Turn-Off Delay Time	$t_{d(off)}$			48	70	
Turn-Off Fall Time	$t_f$			31	45	
Input Capacitance	$C_{iss}$	$V_{DS}=8V, V_{GS}=0V$ $F=1MHz$		22	45	pF
Output Capacitance	$C_{oss}$			11	24	
Reverse Transfer Capacitance	$C_{rss}$			2	5	



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- Typical Performance Characteristics



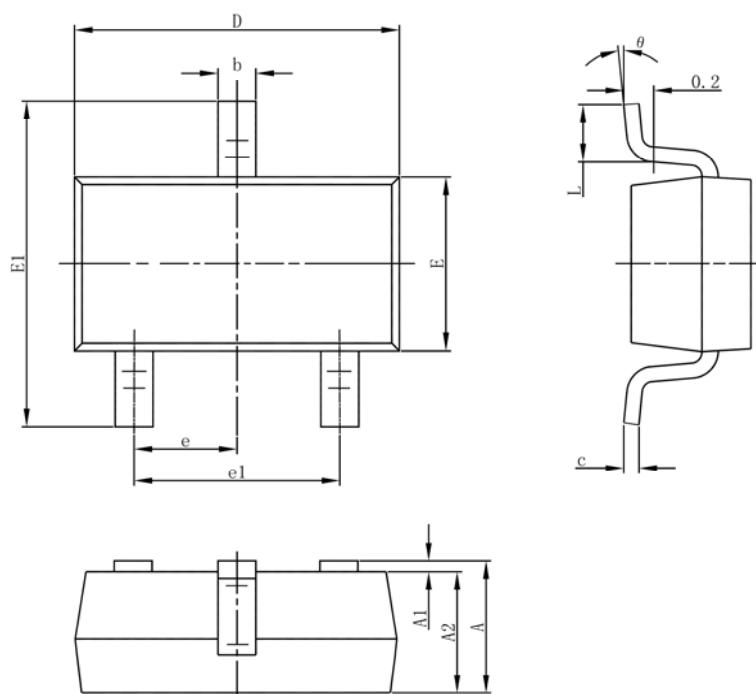


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● Package Information

SOT-23-3L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°
UNIT:mm				